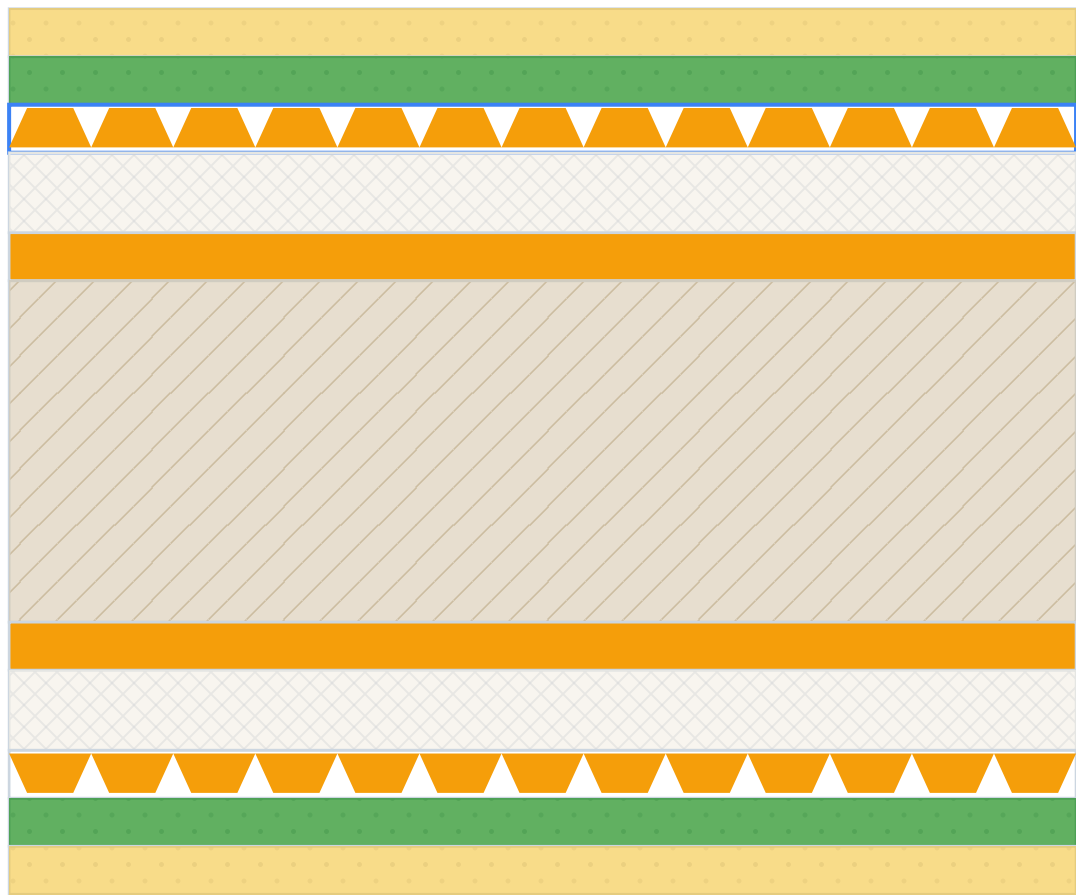


Top Surface Finish
 Top Solder Mask
L1
 Prepreg
L2
 Core
L3
 Prepreg
L4
 Bottom Solder Mask
 Bottom Surface Finish



Spec	Type	Base Thickness	Processed Thickness	RC	DK
ENIG		0.005			
		0.020			
	Signal	0.018	0.018		
FR4 · 7628	Prepreg	0.196	0.1785	43%	4.7
	Plane	0.035	0.035		
FR4	Core	0.63	0.63		4.6
	Plane	0.035	0.035		
FR4 · 7628	Prepreg	0.196	0.1785	43%	4.7
	Signal	0.018	0.018		
		0.020			
ENIG		0.005			

Thickness After Lamination: 1.093 mm
 Finished PCB Thickness: 1.143 mm ±10%
 Inner layer Residual copper ratio: 50%

4L-1.2-7628-1-1-50